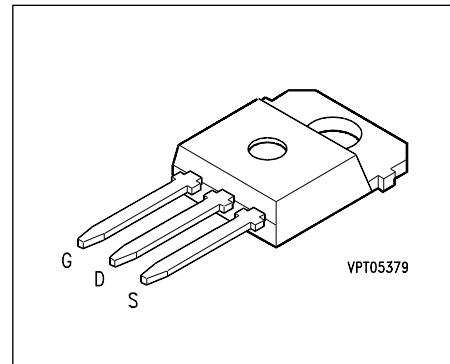


SIPMOS® Power Transistor

BUZ 338

- N channel
- Enhancement mode
- Avalanche-rated



Type	V_{DS}	I_D	$R_{DS\ (on)}$	Package ¹⁾	Ordering Code
BUZ 338	500 V	13.5 A	0.4 Ω	TO-218 AA	C67078-S3126-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current, $T_C = 28^\circ\text{C}$	I_D	13.5	A
Pulsed drain current, $T_C = 25^\circ\text{C}$	$I_{D\ puls}$	54	
Avalanche current, limited by $T_{j\ max}$	I_{AR}	13.5	
Avalanche energy, periodic limited by $T_{j\ (max)}$	E_{AR}	18	mJ
Avalanche energy, single pulse $I_D = 13.5\text{ A}$, $V_{DD} = 50\text{ V}$, $R_{GS} = 25\ \Omega$ $L = 9.09\text{ mH}$, $T_j = 25^\circ\text{C}$	E_{AS}	920	
Gate-source voltage	V_{GS}	± 20	V
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	180	W
Operating and storage temperature range	T_j , T_{stg}	-55 ... +150	°C

Thermal resistance, chip-case	$R_{th\ JC}$	≤ 0.7	K/W
DIN humidity category, DIN 40 040	-	E	-
IEC climatic category, DIN IEC 68-1	-	55/150/56	

1) See chapter Package Outlines.

Electrical Characteristicsat $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static characteristics

Drain-source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}$	$V_{(BR) DSS}$	500	—	—	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	$V_{GS (\text{th})}$	2.1	3.0	4.0	
Zero gate voltage drain current $V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{DSS}	— —	0.1 100	1.0 1000	μA
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	—	10	100	nA
Drain-source on-resistance $V_{GS} = 10 \text{ V}, I_D = 8.5 \text{ A}$	$R_{DS (\text{on})}$	—	0.3	0.4	Ω

Dynamic characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}, I_D = 8.5 \text{ A}$	g_{fs}	8.0	15	—	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	—	2500	3325	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	—	320	480	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	—	120	180	
Turn-on time t_{on} , ($t_{on} = t_{d(on)} + t_r$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2.9 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(on)}$ t_r	— —	40 100	60 150	ns
Turn-off time t_{off} , ($t_{off} = t_{d(off)} + t_f$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2.9 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(off)}$ t_f	— —	450 120	600 160	

Electrical Characteristics (cont'd)
at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

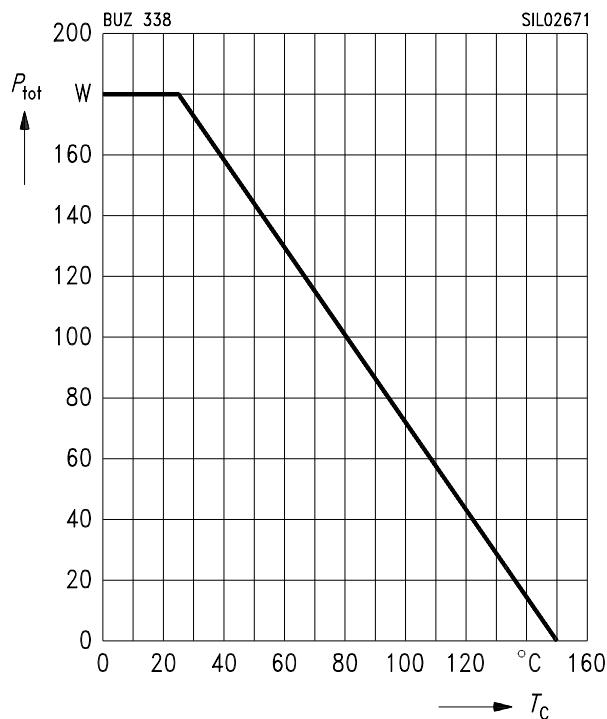
Reverse diode

Continuous reverse drain current $T_C = 25^\circ\text{C}$	I_S	—	—	13.5	A
Pulsed reverse drain current $T_C = 25^\circ\text{C}$	I_{SM}	—	—	54	
Diode forward on-voltage $I_S = 27 \text{ A}$, $V_{GS} = 0 \text{ V}$	V_{SD}	—	1.1	1.6	V
Reverse recovery time $V_R = 100 \text{ V}$, $I_F = I_S$, $di_F / dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	—	400	—	ns
Reverse recovery charge $V_R = 100 \text{ V}$, $I_F = I_S$, $di_F / dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	—	6.2	—	μC

Characteristics at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Total power dissipation

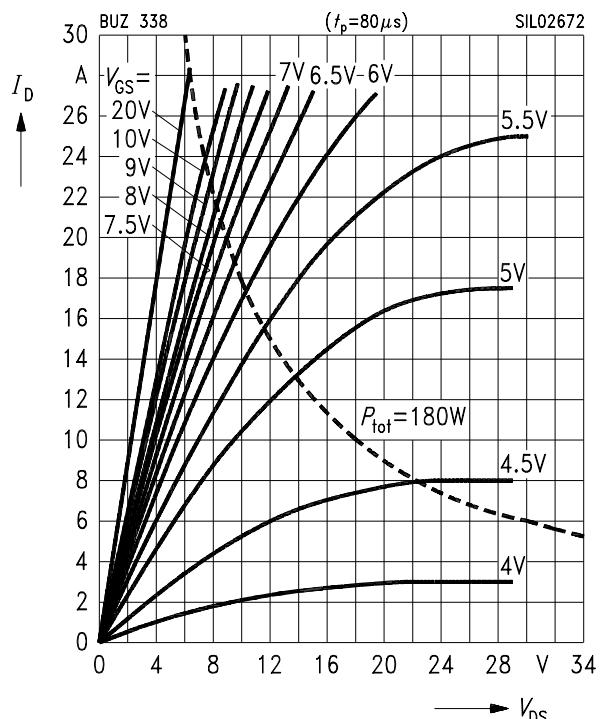
$$P_{\text{tot}} = f(T_C)$$



Typ. output characteristics

$$I_D = f(V_{DS})$$

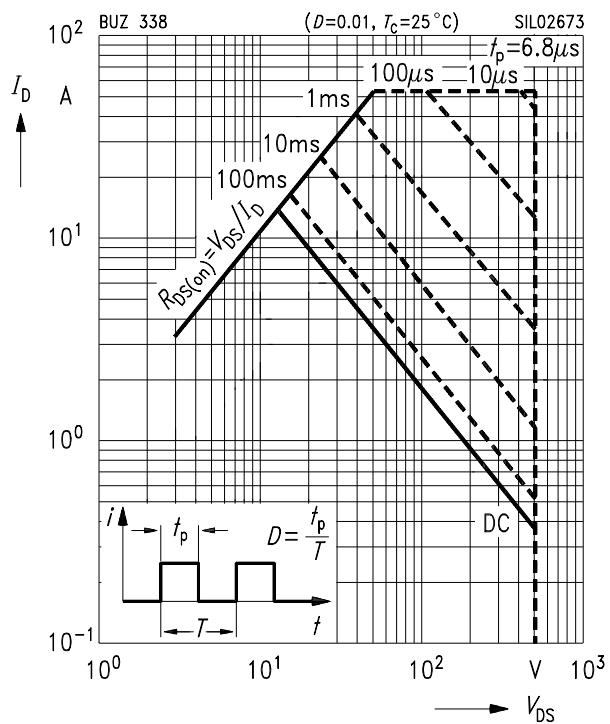
parameter: $t_p = 80 \mu\text{s}$



Safe operating area

$$I_D = f(V_{DS})$$

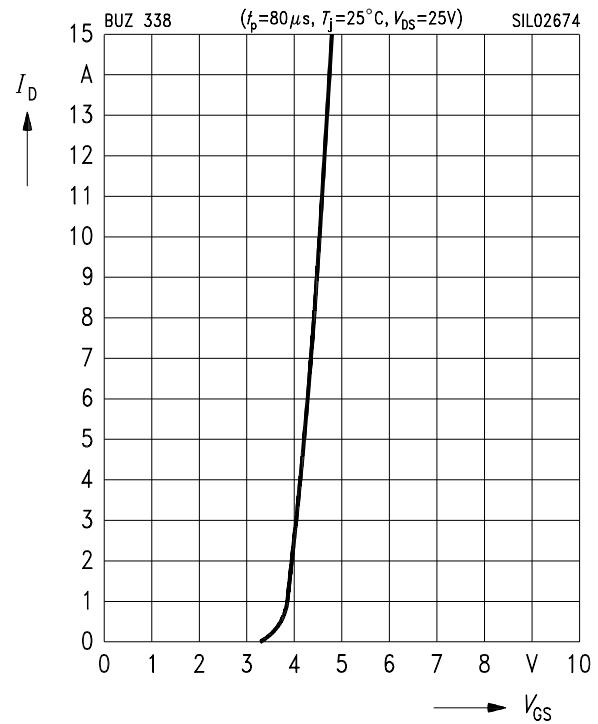
parameter: $D = 0.01$, $T_C = 25^\circ\text{C}$



Typ. transfer characteristics

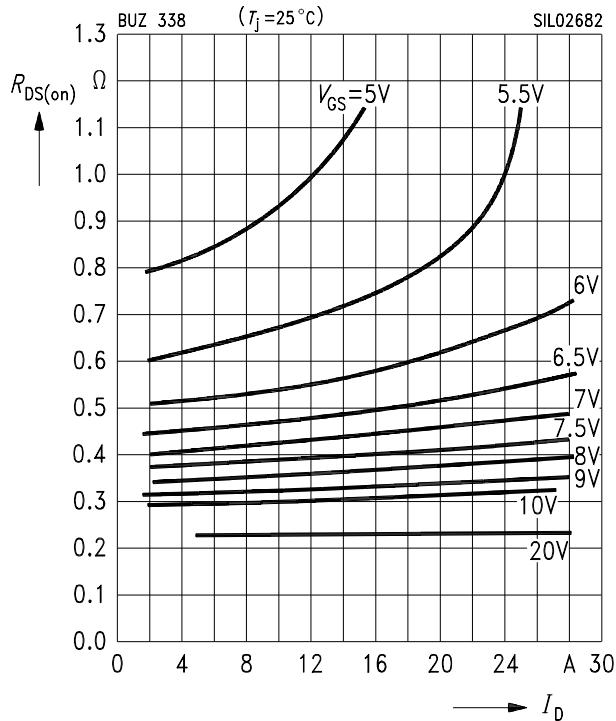
$$I_D = f(V_{GS})$$

parameter: $t_p = 80 \mu\text{s}$, $V_{DS} = 25 \text{ V}$



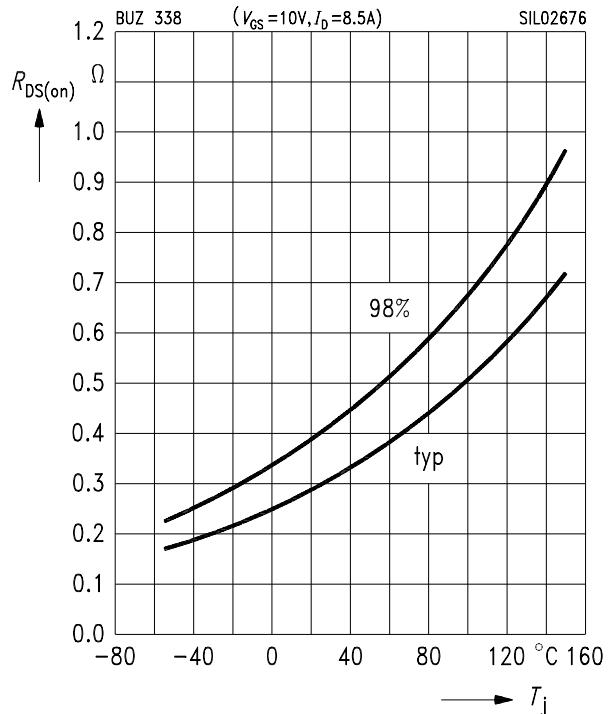
Typ. drain-source on-resistance

$R_{DS(on)} = f(I_D)$
parameter: V_{GS}



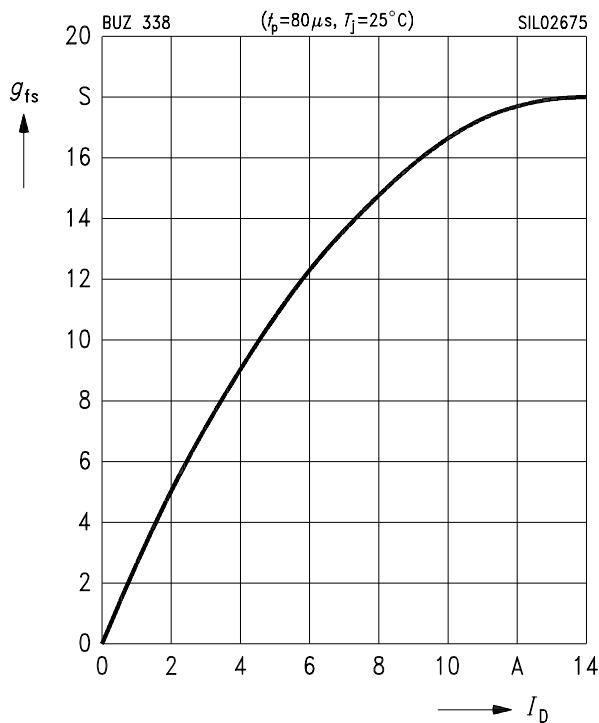
Drain-source on-resistance

$R_{DS(on)} = f(T_j)$
parameter: $I_D = 8.5 \text{ A}$, $V_{GS} = 10 \text{ V}$, (spread)



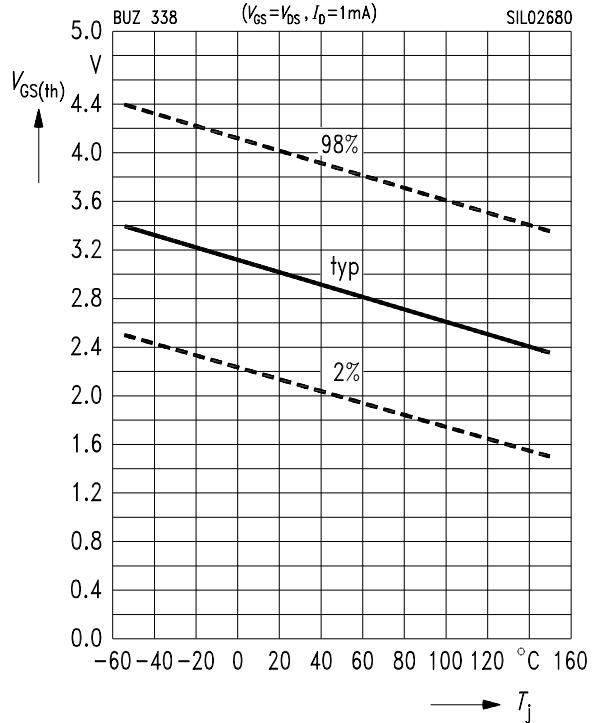
Typ.forward transconductance

$g_{fs} = f(I_D)$
parameter: $t_p = 80 \mu\text{s}$



Gate threshold voltage

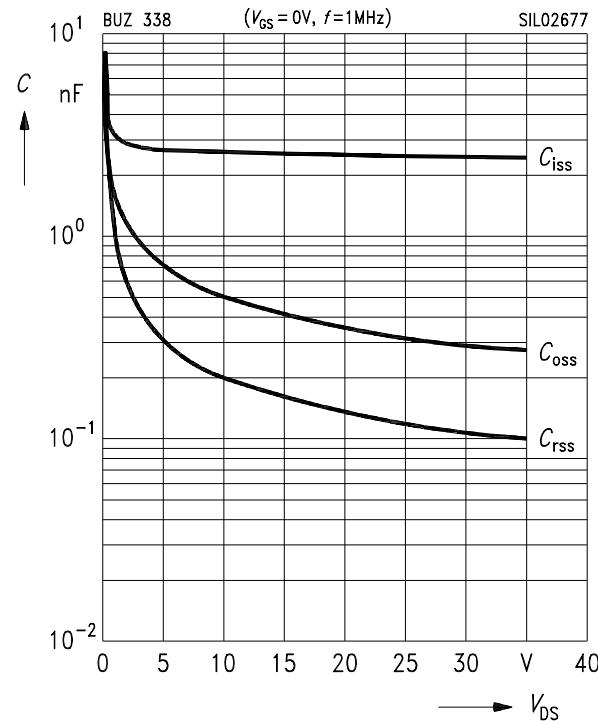
$V_{GS(th)} = f(T_j)$
parameter: $V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$, (spread)



Typ. capacitances

$$C = f(V_{DS})$$

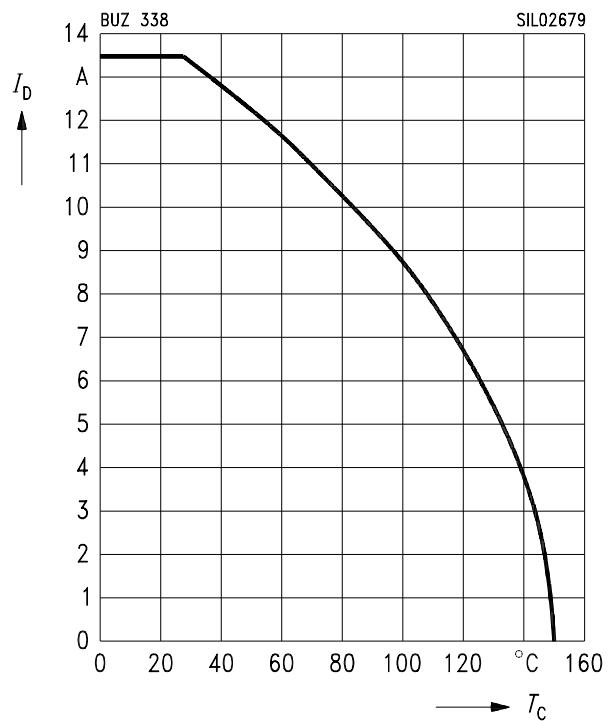
parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$



Drain current

$$I_D = f(T_C)$$

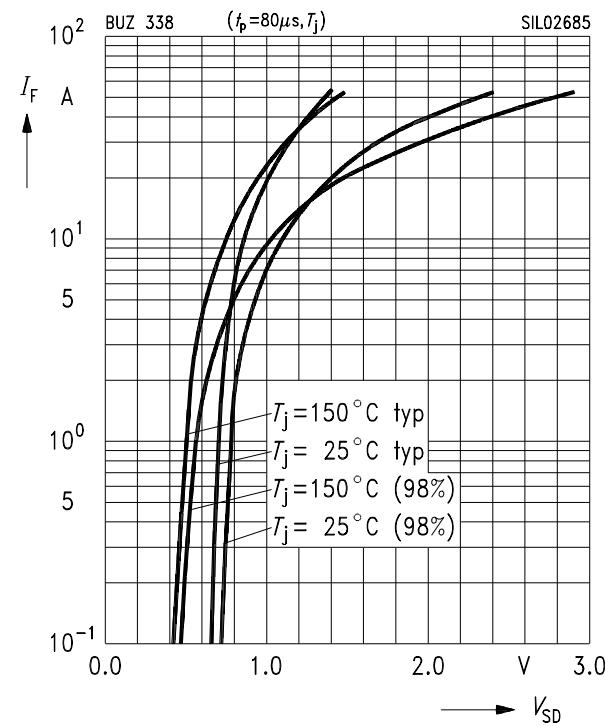
parameter: $V_{GS} \geq 10 \text{ V}$



Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

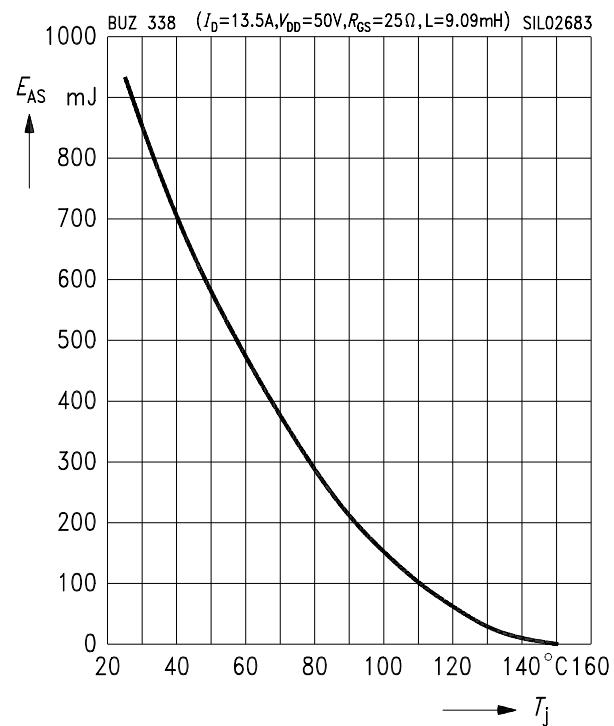
parameter: T_j , $t_p = 80 \mu\text{s}$



Avalanche energy $E_{AS} = f(T_j)$

parameter: $I_D = 13.5 \text{ A}$, $V_{DD} = 50 \text{ V}$

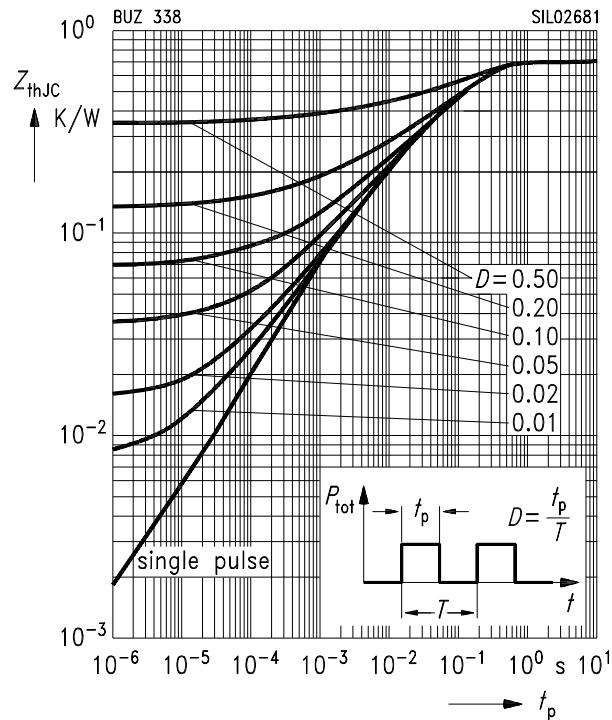
$R_{GS} = 25 \Omega$, $L = 9.09 \text{ mH}$



Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

parameter: $D = t_p / T$



Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

parameter: $I_D \text{ puls} = 20.3 \text{ A}$

